

74LCX541

Low Voltage Octal Buffer/Line Driver with 5V Tolerant Inputs and Outputs

General Description

The LCX541 is an octal buffer/line driver designed to be employed as memory and address drivers, clock drivers and bus oriented transmitter/receivers. The LCX541 is a non inverting option of the LCX540.

This device is similar in function to the LCX244 while providing flow-through architecture (inputs on opposite side from outputs). This pinout arrangement makes this device especially useful as an output port for microprocessors, allowing ease of layout and greater PC board density.

The LCX541 is designed for low voltage (2.5V or 3.3V) V_{CC} applications with capability of interfacing to a 5V signal environment. The LCX541 is fabricated with an advanced CMOS technology to achieve high speed operation while maintaining CMOS low power dissipation.

Features

- 5V tolerant input and outputs
- 2.3V–3.6V V_{CC} specifications provided
- 6.5 ns t_{PD} max ($V_{CC} = 3.3V$), 10 μA I_{CC} max
- Power-down high impedance inputs and outputs
- Supports live insertion/withdrawal (Note 1)
- ± 24 mA output drive ($V_{CC} = 3.0V$)
- Implements patented noise/ EMI reduction circuitry
- Latch-up performance exceeds JEDEC 78 conditions
- ESD performance:
 - Human body model > 2000V
 - Machine model > 200V
- Leadless Pb-Free DQFN package

Note 1: To ensure the high-impedance state during power up or down, \overline{OE} should be tied to V_{CC} through a pull-up resistor: the minimum value or the resistor is determined by the current-sourcing capability of the driver.

Ordering Code:

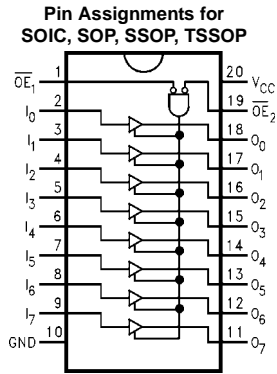
| Order Number | Package Number | Package Description |
|--|----------------|---|
| 74LCX541WM | M20B | 20-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-013, 0.300" Wide |
| 74LCX541SJ | M20D | Pb-Free 20-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide |
| 74LCX541BQX (Preliminary) (Note 2) | MLP020B | Pb-Free 20-Terminal Depopulated Quad Very-Thin Flat Pack No Leads (DQFN), JEDEC MO-241, 2.5 x 4.5mm |
| 74LCX541MSA | MSA20 | 20-Lead Shrink Small Outline Package (SSOP), JEDEC MO-150, 5.3mm Wide |
| 74LCX541MTC | MTC20 | 20-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide |
| 74LCX541MTC_NL (Note 3) | MTC20 | Pb-Free 20-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide |

Devices also available in Tape and Reel. Specify by appending the suffix letter "X" to the ordering code.
Pb-Free package per JEDEC J-STD-020B.

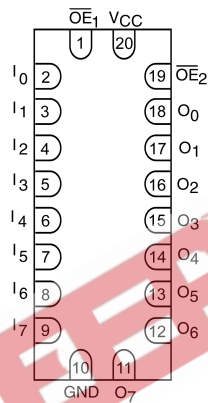
Note 2: DQFN package available in Tape and Reel only.

Note 3: "_NL" indicates Pb-Free package (per JEDEC J-STD-020B). Device available in Tape and Reel only.

Connection Diagrams

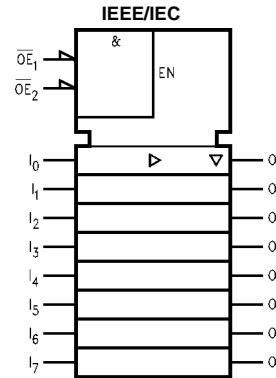


Pad Assignment for DQFN



(Top View)

Logic Symbol



Pin Descriptions

| Pin Names | Description |
|------------------------------------|------------------------------|
| $\overline{OE}_1, \overline{OE}_2$ | 3-STATE Output Enable Inputs |
| I_0, I_7 | Inputs |
| O_0, O_7 | Outputs |

Truth Table

| Inputs | | | Outputs |
|-------------------|-------------------|---|---------|
| \overline{OE}_1 | \overline{OE}_2 | I | O_n |
| L | L | H | H |
| H | X | X | Z |
| X | H | X | Z |
| L | L | L | L |

H = HIGH Voltage Level
 L = LOW Voltage Level
 X = Immaterial
 Z = High Impedance

| Absolute Maximum Ratings (Note 4) | | | | | | |
|--|---|--|---|--------------------------------------|-----------|---------|
| Symbol | Parameter | Value | Conditions | Units | | |
| V_{CC} | Supply Voltage | -0.5 to +7.0 | | V | | |
| V_I | DC Input Voltage | -0.5 to +7.0 | | V | | |
| V_O | DC Output Voltage | -0.5 to +7.0 -0.5 to $V_{CC} + 0.5$ | Output in 3-STATE Output in HIGH or LOW State (Note 5) | V | | |
| I_{IK} | DC Input Diode Current | -50 | $V_I < GND$ | mA | | |
| I_{OK} | DC Output Diode Current | -50 +50 | $V_O < GND$ $V_O > V_{CC}$ | mA | | |
| I_O | DC Output Source/Sink Current | ± 50 | | mA | | |
| I_{CC} | DC Supply Current per Supply Pin | ± 100 | | mA | | |
| I_{GND} | DC Ground Current per Ground Pin | ± 100 | | mA | | |
| T_{STG} | Storage Temperature | -65 to +150 | | °C | | |
| Recommended Operating Conditions (Note 6) | | | | | | |
| Symbol | Parameter | Min | Max | Units | | |
| V_{CC} | Supply Voltage | Operating | 2.0 | 3.6 | V | |
| | | Data Retention | 1.5 | 3.6 | | |
| V_I | Input Voltage | 0 | 5.5 | V | | |
| V_O | Output Voltage | HIGH or LOW State | 0 | V_{CC} | V | |
| | | 3-STATE | 0 | 5.5 | | |
| I_{OH}/I_{OL} | Output Current | $V_{CC} = 3.0V - 3.6V$ | | ± 24 | mA | |
| | | $V_{CC} = 2.7V - 3.0V$ | | ± 12 | | |
| | | $V_{CC} = 2.3V - 2.7V$ | | ± 8 | | |
| T_A | Free-Air Operating Temperature | -40 | 85 | °C | | |
| $\Delta t/\Delta V$ | Input Edge Rate, $V_{IN} = 0.8V - 2.0V$, $V_{CC} = 3.0V$ | 0 | 10 | ns/V | | |
| <p>Note 4: The Absolute Maximum Ratings are those values beyond which the safety of the device cannot be guaranteed. The device should not be operated at these limits. The parametric values defined in the Electrical Characteristics tables are not guaranteed at the Absolute Maximum Ratings. The "Recommended Operating Conditions" table will define the conditions for actual device operation.</p> <p>Note 5: I_O Absolute Maximum Rating must be observed.</p> <p>Note 6: Unused inputs or I/O's must be held HIGH or LOW. They may not float.</p> | | | | | | |
| DC Electrical Characteristics | | | | | | |
| Symbol | Parameter | Conditions | V_{CC} (V) | $T_A = -40^\circ C$ to $+85^\circ C$ | | Units |
| | | | | Min | Max | |
| V_{IH} | HIGH Level Input Voltage | | 2.3 - 2.7 | 1.7 | | V |
| | | | 2.7 - 3.6 | 2.0 | | |
| V_{IL} | LOW Level Input Voltage | | 2.3 - 2.7 | | 0.7 | V |
| | | | 2.7 - 3.6 | | 0.8 | |
| V_{OH} | HIGH Level Output Voltage | $I_{OH} = -100\mu A$ | 2.3 - 3.6 | $V_{CC} - 0.2$ | | V |
| | | $I_{OH} = -8\text{ mA}$ | 2.3 | 1.8 | | |
| | | $I_{OH} = -12\text{ mA}$ | 2.7 | 2.2 | | |
| | | $I_{OH} = -18\text{ mA}$ | 3.0 | 2.4 | | |
| | | $I_{OH} = -24\text{ mA}$ | 3.0 | 2.2 | | |
| V_{OL} | LOW Level Output Voltage | $I_{OL} = 100\mu A$ | 2.3 - 3.6 | | 0.2 | V |
| | | $I_{OL} = 8\text{ mA}$ | 2.3 | | 0.6 | |
| | | $I_{OL} = 12\text{ mA}$ | 2.7 | | 0.4 | |
| | | $I_{OL} = 16\text{ mA}$ | 3.0 | | 0.4 | |
| | | $I_{OL} = 24\text{ mA}$ | 3.0 | | 0.55 | |
| I_I | Input Leakage Current | $0 \leq V_I \leq 5.5V$ | 2.3 - 3.6 | | ± 5.0 | μA |
| I_{OFF} | Power-Off Leakage Current | V_I or $V_O = 5.5V$ | 0 | | 10 | μA |
| I_{CC} | Quiescent Supply Current | $V_I = V_{CC}$ or GND | 2.3 - 3.6 | | 10 | μA |
| | | $3.6V \leq V_I$, $V_O \leq 5.5V$ (Note 7) | 2.3 - 3.6 | | ± 10 | |
| ΔI_{CC} | Increase in I_{CC} per Input | $V_{IH} = V_{CC} = 0.6V$ | 2.3 - 3.6 | | 500 | μA |

DC Electrical Characteristics (Continued)

Note 7: Outputs disabled or 3-STATE only.

AC Electrical Characteristics

| Symbol | Parameter | $T_A = -40^\circ\text{C to } +85^\circ\text{C}, R_L = 500\Omega$ | | | | | | Units |
|------------|--------------------------------|--|-----|----------------------|-----|--------------------------|------|-------|
| | | $V_{CC} = 3.3V \pm 0.3V$ | | $V_{CC} = 2.7V$ | | $V_{CC} = 2.5V \pm 0.2V$ | | |
| | | $C_L = 50\text{ pF}$ | | $C_L = 50\text{ pF}$ | | $C_L = 30\text{ pF}$ | | |
| | | Min | Max | Min | Max | Min | Max | |
| t_{PHL} | Propagation Delay | 1.5 | 6.5 | 1.5 | 7.5 | 1.5 | 7.8 | ns |
| t_{PLH} | | 1.5 | 6.5 | 1.5 | 7.5 | 1.5 | 7.8 | |
| t_{PZL} | Output Enable Time | 1.5 | 8.5 | 1.5 | 9.5 | 1.5 | 10.5 | ns |
| t_{PZH} | | 1.5 | 8.5 | 1.5 | 9.5 | 1.5 | 10.5 | |
| t_{PLZ} | Output Disable Time | 1.5 | 7.5 | 1.5 | 8.5 | 1.5 | 9.0 | ns |
| t_{PHZ} | | 1.5 | 7.5 | 1.5 | 8.5 | 1.5 | 9.0 | |
| t_{OSHL} | Output to Output Skew (Note 8) | | 1.0 | | | | | ns |
| t_{OSLH} | | | 1.0 | | | | | |

Note 8: Skew is defined as the absolute value of the difference between the actual propagation delay for any two separate outputs of the same device. The specification applies to any outputs switching in the same direction, either HIGH-to-LOW (t_{OSHL}) or LOW-to-HIGH (t_{OSLH}).

Dynamic Switching Characteristics

| Symbol | Parameter | Conditions | V_{CC} (V) | $T_A = 25^\circ\text{C}$ | Units |
|-----------|--------------------------------------|--|-----------------|--------------------------|-------|
| | | | | Typical | |
| V_{OLP} | Quiet Output Dynamic Peak V_{OL} | $C_L = 50\text{ pF}, V_{IH} = 3.3V, V_{IL} = 0V$ $C_L = 30\text{ pF}, V_{IH} = 2.5V, V_{IL} = 0V$ | 3.3 | 0.8 | V |
| | | | | 2.5 | |
| V_{OLV} | Quiet Output Dynamic Valley V_{OL} | $C_L = 50\text{ pF}, V_{IH} = 3.3V, V_{IL} = 0V$ $C_L = 30\text{ pF}, V_{IH} = 2.5V, V_{IL} = 0V$ | 3.3 | -0.8 | V |
| | | | | 2.5 | |

Capacitance

| Symbol | Parameter | Conditions | Typical | Units |
|-----------|-------------------------------|---|---------|-------|
| C_{IN} | Input Capacitance | $V_{CC} = \text{Open}, V_I = 0V \text{ or } V_{CC}$ | 7 | pF |
| C_{OUT} | Output Capacitance | $V_{CC} = 3.3V, V_I = 0V \text{ or } V_{CC}$ | 8 | pF |
| C_{PD} | Power Dissipation Capacitance | $V_{CC} = 3.3V, V_I = 0V \text{ or } V_{CC}, f = 10\text{ MHz}$ | 25 | pF |

AC Loading and Waveforms Generic for LCX Family

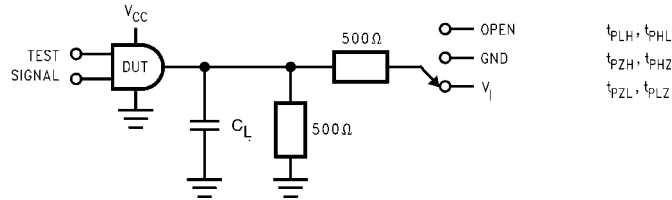
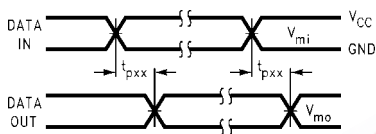
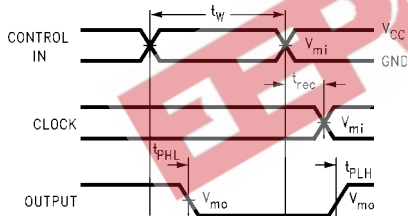


FIGURE 1. AC Test Circuit
(C_L includes probe and jig capacitance)

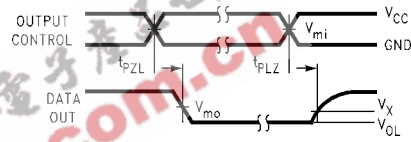
| Test | Switch |
|--------------------|---|
| t_{PLH}, t_{PHL} | Open |
| t_{PZL}, t_{PLZ} | 6V at $V_{CC} = 3.3 \pm 0.3V$ $V_{CC} \times 2$ at $V_{CC} = 2.5 \pm 0.2V$ |
| t_{PZH}, t_{PHZ} | GND |



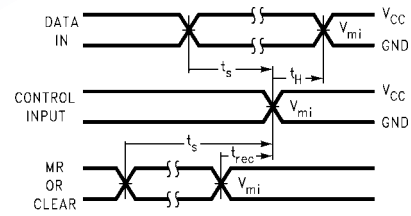
Waveform for Inverting and Non-Inverting Functions



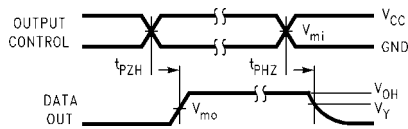
Propagation Delay, Pulse Width and t_{rec} Waveforms



3-STATE Output Low Enable and Disable Times for Logic



Setup Time, Hold Time and Recovery Time for Logic



3-STATE Output High Enable and Disable Times for Logic

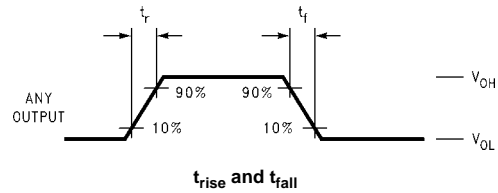
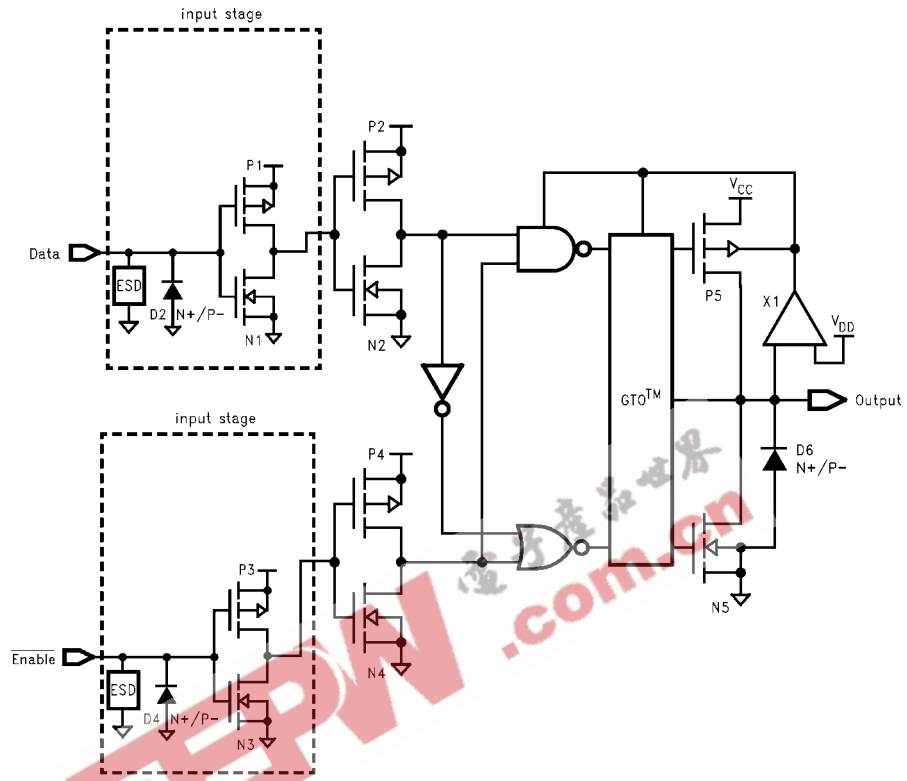


FIGURE 2. Waveforms
(Input Pulse Characteristics; $f = 1MHz, t_r = t_f = 3ns$)

| Symbol | V_{CC} | | |
|----------|-----------------|-----------------|------------------|
| | $3.3V \pm 0.3V$ | $2.7V$ | $2.5V \pm 0.2V$ |
| V_{mi} | 1.5V | 1.5V | $V_{CC}/2$ |
| V_{mo} | 1.5V | 1.5V | $V_{CC}/2$ |
| V_x | $V_{OL} + 0.3V$ | $V_{OL} + 0.3V$ | $V_{OL} + 0.15V$ |
| V_y | $V_{OH} - 0.3V$ | $V_{OH} - 0.3V$ | $V_{OH} - 0.15V$ |

Schematic Diagram Generic for LCX Family



Tape and Reel Specification

Tape Format for DQFN

| Package Designator | Tape Section | Number Cavities | Cavity Status | Cover Tape Status |
|--------------------|--------------------|-----------------|---------------|-------------------|
| BQX | Leader (Start End) | 125 (typ) | Empty | Sealed |
| | Carrier | 3000 | Filled | Sealed |
| | Trailer (Hub End) | 75 (typ) | Empty | Sealed |

TAPE DIMENSIONS inches (millimeters)

| PKG. SIZE | DIM.A ₀ | DIM.B ₀ | DIM.K ₀ |
|-----------|--------------------|--------------------|--------------------|
| 3.5 X 4.5 | 3.8 ± 0.1 | 4.8 ± 0.1 | 0.9 ± 0.1 |
| 3.0 X 3.0 | 3.3 ± 0.1 | 3.3 ± 0.1 | 0.9 ± 0.1 |
| 2.5 X 4.5 | 2.8 ± 0.1 | 4.8 ± 0.1 | 0.9 ± 0.1 |
| 2.5 X 3.5 | 2.8 ± 0.1 | 3.8 ± 0.1 | 0.9 ± 0.1 |
| 2.5 X 3.0 | 2.8 ± 0.1 | 3.3 ± 0.1 | 0.9 ± 0.1 |
| 2.5 X 2.5 | 2.8 ± 0.1 | 2.8 ± 0.1 | 0.9 ± 0.1 |

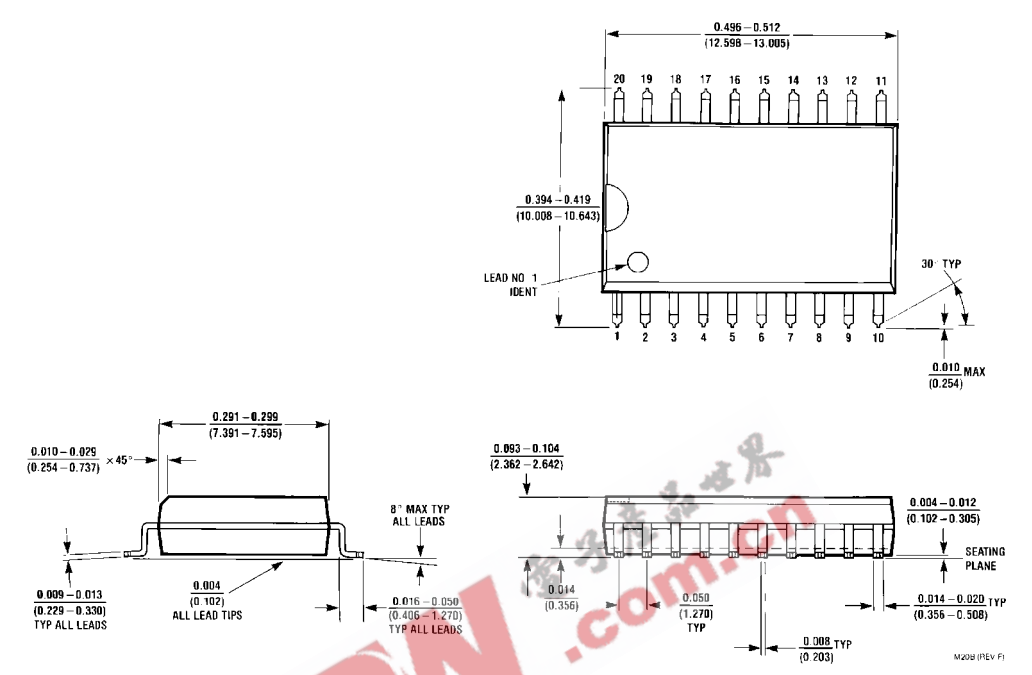
DIMENSIONS ARE IN MILLIMETERS

- NOTES: unless otherwise specified
- Cumulative pitch for feeding holes and cavities (chip pockets) not to exceed 0.008[0.20] over 10 pitch span.
 - Smallest allowable bending radius.
 - Thru hole inside cavity is centered within cavity.
 - Tolerance is ±0.002[0.05] for these dimensions on all 12mm tapes.
 - A₀ and B₀ measured on a plane 0.120[0.30] above the bottom of the pocket.
 - K₀ measured from a plane on the inside bottom of the pocket to the top surface of the carrier.
 - Pocket position relative to sprocket hole measured as true position of pocket. Not pocket hole.
 - Controlling dimension is millimeter. Dimension in inches rounded.

REEL DIMENSIONS inches (millimeters)

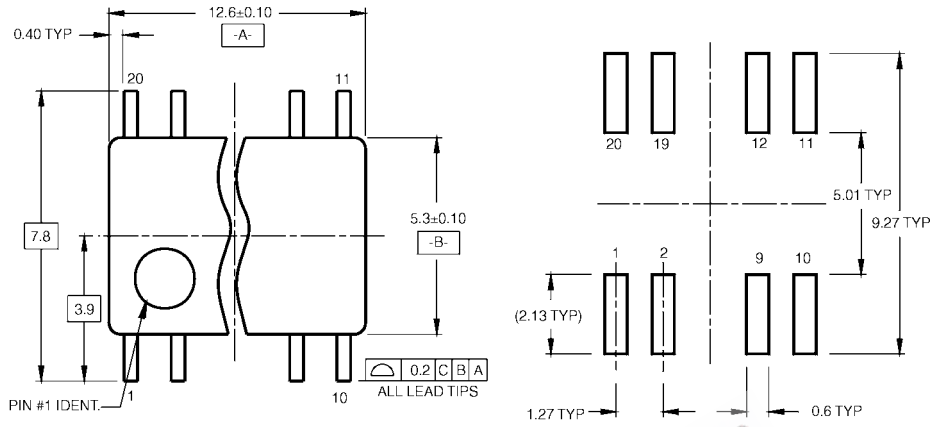
| Tape Size | A | B | C | D | N | W1 | W2 |
|-----------|-----------------|-----------------|------------------|------------------|------------------|-----------------|-----------------|
| 12 mm | 13.0 (330.0) | 0.059 (1.50) | 0.512 (13.00) | 0.795 (20.20) | 2.165 (55.00) | 0.488 (12.4) | 0.724 (18.4) |

Physical Dimensions inches (millimeters) unless otherwise noted

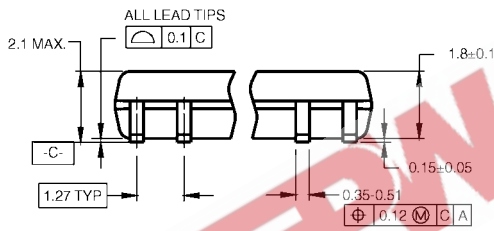


**20-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-013, 0.300" Wide
Package Number M20B**

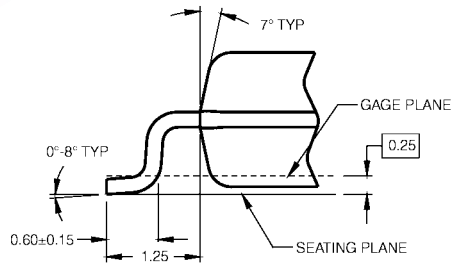
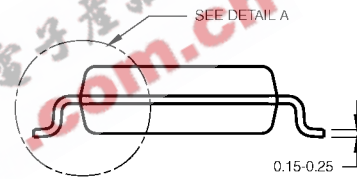
Physical Dimensions inches (millimeters) unless otherwise noted (Continued)



LAND PATTERN RECOMMENDATION



DIMENSIONS ARE IN MILLIMETERS



DETAIL A

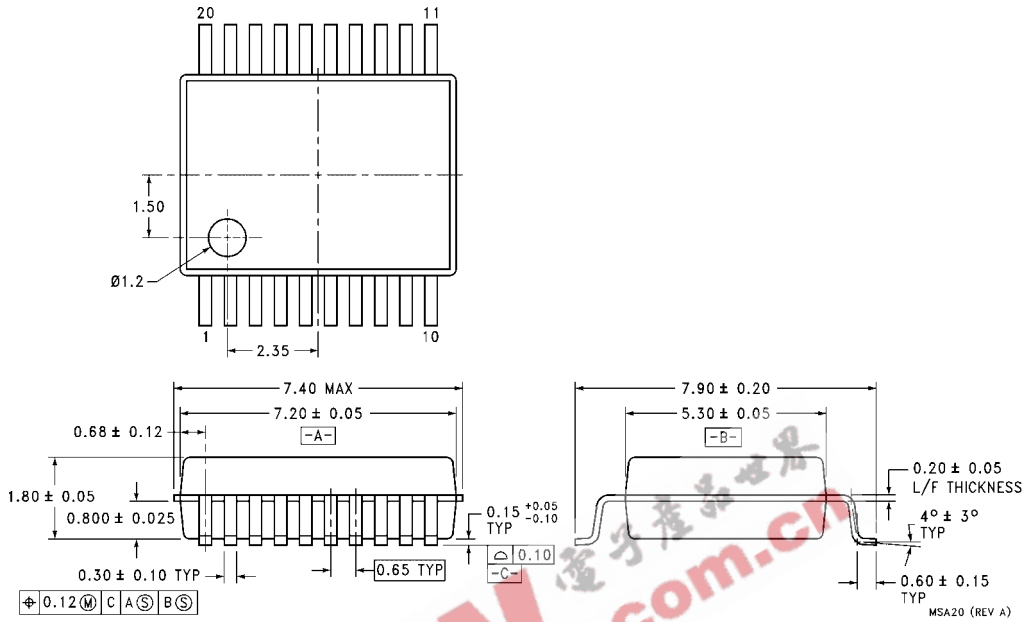
NOTES:

- A. CONFORMS TO EIAJ EDR-7320 REGISTRATION, ESTABLISHED IN DECEMBER, 1998.
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.

M20DRevB1

**Pb-Free 20-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide
Package Number M20D**

Physical Dimensions inches (millimeters) unless otherwise noted (Continued)



20-Lead Shrink Small Outline Package (SSOP), JEDEC MO-150, 5.3mm Wide
Package Number MSA20

Physical Dimensions inches (millimeters) unless otherwise noted (Continued)

DIMENSIONS ARE IN MILLIMETERS

NOTES:

- A. CONFORMS TO JEDEC REGISTRATION MO-153, VARIATION AC, REF NOTE 6, DATE 7/93.
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLDS FLASH, AND TIE BAR EXTRUSIONS.
- D. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M, 1982.

MTC20REV D1

**20-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide
Package Number MTC20**

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